

Title (en)

FLUID EJECTION DEVICE, METHOD OF FORMING FLUID EJECTION DEVICE AND FLUID EJECTION SYSTEM

Title (de)

FLÜSSIGKEITSAUSSTOSSVORRICHTUNG, VERFAHREN ZUR HERSTELLUNG EINER FLÜSSIGKEITSAUSSTOSSVORRICHTUNG UND FLÜSSIGKEITSAUSSTOSSSYSTEM

Title (fr)

DISPOSITIF D'ÉJECTION DE FLUIDE, PROCÉDÉ DE FORMATION D'UN DISPOSITIF D'ÉJECTION DE FLUIDE ET SYSTÈME D'ÉJECTION DE FLUIDE

Publication

**EP 3277430 B1 20220309 (EN)**

Application

**EP 16771755 A 20160325**

Priority

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- JP 2016001756 W 20160325

Abstract (en)

[origin: WO2016157867A1] A fluid ejection device (100) includes a body (102) defining an interior bore (108), a fluid reservoir (110), and a fluid ejection chip (130). The fluid reservoir (110) defines an interior passage (185) that receives a fluid, the interior passage(185) in fluid communication with the interior bore (108) of the body (102). The fluid ejection chip (130) is coupled with the body (102) and includes one or more fluid ejection actuators. The fluid ejection chip (130) has one or more interior fluid paths in fluid communication with the interior bore (108) of the body (102) so that the fluid ejection chip (130) ejects the fluid upon activation of the one or more fluid ejection actuators.

IPC 8 full level

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CPC (source: EP)

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